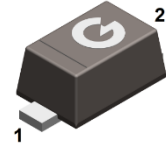


Features

- ESD / transient protection of high speed data lines
 - IEC 61000-4-2 (ESD): ± 30 kV (air), ± 30 kV (contact)
- Working voltage: $V_{RWM} = 3.3V$
- Low leakage current
- Low clamping voltage
- RoHS compliant with Halogen-free

HF



SOD-523

Mechanical Data

- Case: SOD-523
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
GESD3V3D5	SOD-523	3000 pcs / Tape & Reel	N1

Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
IEC 61000-4-2; ESD (Air)	V_{ESD-A}	± 30	kV
IEC 61000-4-2; ESD (Contact)	V_{ESD-C}	± 30	kV
Reverse Working Voltage	V_{RWM}	3.3	V
Peak Pulse Power ($t_p = 8/20\mu\text{s}$)	P_{PP}	330	W
Peak Pulse Current ($t_p = 8/20\mu\text{s}$)	I_{PP}	18	A

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-to-Air ^{*1}	$R_{\theta JA}$	320	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Case ^{*1}	$R_{\theta JC}$	220	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Lead ^{*1}	$R_{\theta JL}$	230	$^\circ\text{C/W}$
Operating Junction Temperature Range	T_J	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 ~ +150	$^\circ\text{C}$

Note 1: The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V_{BR}	Reverse Breakdown Voltage	$I_T = 5\text{mA}$	5.2	-	6	V
I_R	Reverse Leakage Current	$V_{RWM} = 3.3\text{V}$	-	-	2	μA
V_C	Clamping Voltage	$I_{PP} = 1\text{A}$, $t_p = 8/20\mu\text{s}$	-	-	7	V
		$I_{PP} = 18\text{A}$, $t_p = 8/20\mu\text{s}$	-	-	20	V
C_J	Junction Capacitance	$V_R = 0\text{V}$, $f = 1.0\text{MHz}$	-	-	300	pF

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

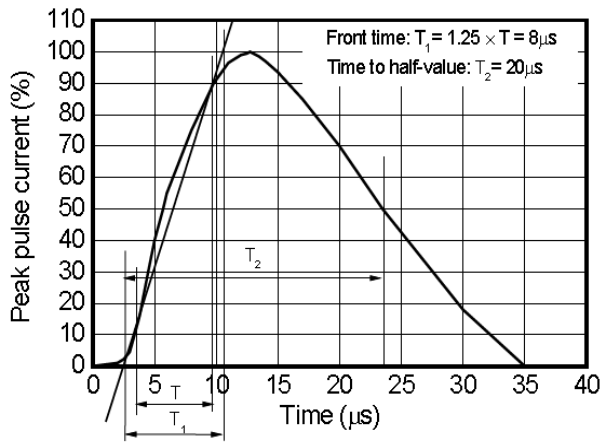


Fig 1 8/20 μs waveform per IEC61000-4-5

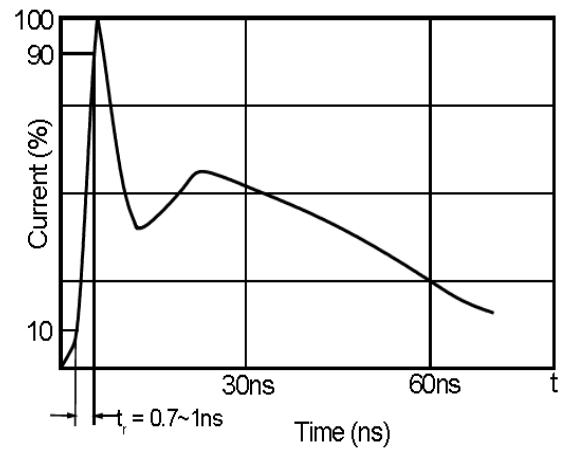


Fig 2 ESD pulse waveform according to IEC61000-4-2

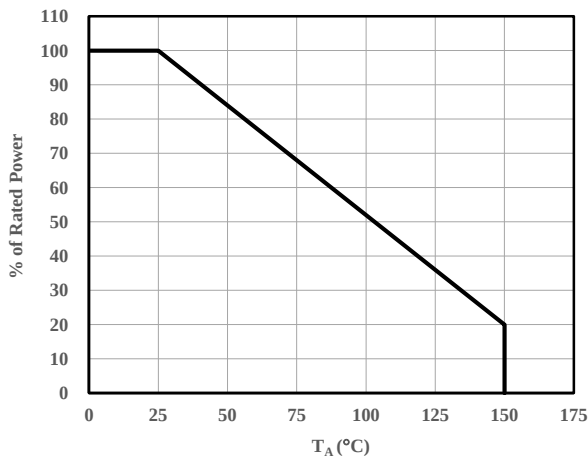


Fig 3 Power Derating Curve

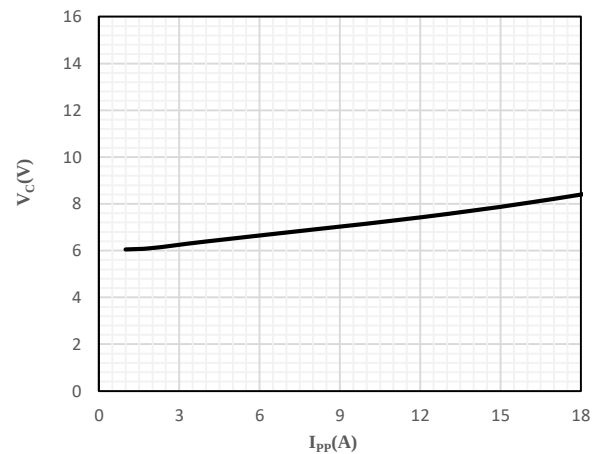


Fig 4 Clamping Voltage vs. Peak Pulse Current

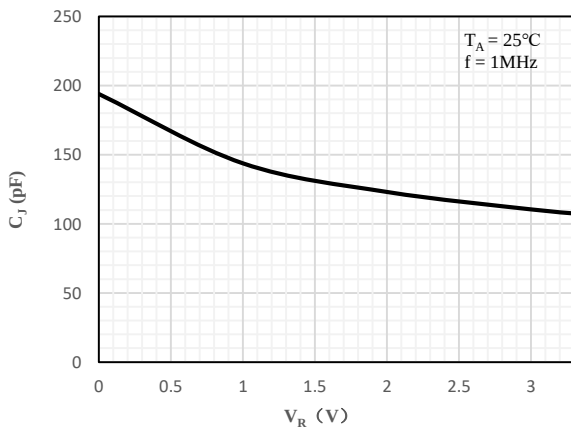
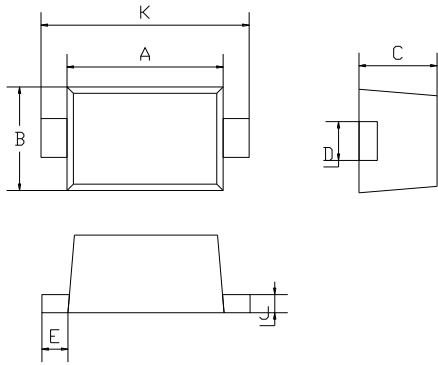


Fig 5 Junction Capacitance vs. Reverse Voltage

Package Outline Dimensions (Unit: mm)



SOD-523		
Dimension	Min.	Max.
A	1.10	1.30
B	0.70	0.90
C	0.50	0.70
D	0.25	0.35
E	0.15	0.25
J	0.05	0.15
K	1.50	1.70

Package Outline Dimensions (Unit: mm)

SOD-523

